

Solder Spheres for BGAs

Product Highlights

Chip Quik® BGA solder spheres are manufactured from virgin materials to meet or exceed the requirements of building or repairing BGA packages. Chip Quik® BGA solder spheres also exceed both the IPC and MIL standards for purity levels and size tolerances. Nominal sizes are available from 12 to 30 mil.

Product Specifications

| Part Number | Alloy | Melting Point | Diameter | Quantity (by weight) |
|----------------------|--------------------|-----------------------|--------------------------|----------------------|
| SMD2165 | Sn63/Pb37 | 183°C (361°F) | 0.012" (0.3048mm) | 250,000 |
| SMD2165-25000 | Sn63/Pb37 | 183°C (361°F) | 0.012" (0.3048mm) | 25,000 |
| SMD2180 | Sn63/Pb37 | 183°C (361°F) | 0.016" (0.4064mm) | 250,000 |
| SMD2180-25000 | Sn63/Pb37 | 183°C (361°F) | 0.016" (0.4064mm) | 25,000 |
| SMD2190 | Sn63/Pb37 | 183°C (361°F) | 0.020" (0.5080mm) | 250,000 |
| SMD2190-25000 | Sn63/Pb37 | 183°C (361°F) | 0.020" (0.5080mm) | 25,000 |
| SMD2200 | Sn63/Pb37 | 183°C (361°F) | 0.024" (0.6096mm) | 250,000 |
| SMD2200-25000 | Sn63/Pb37 | 183°C (361°F) | 0.024" (0.6096mm) | 25,000 |
| SMD2205 | Sn63/Pb37 | 183°C (361°F) | 0.025" (0.6350mm) | 250,000 |
| SMD2205-25000 | Sn63/Pb37 | 183°C (361°F) | 0.025" (0.6350mm) | 25,000 |
| SMD2215 | Sn63/Pb37 | 183°C (361°F) | 0.030" (0.7620mm) | 250,000 |
| SMD2215-25000 | Sn63/Pb37 | 183°C (361°F) | 0.030" (0.7620mm) | 25,000 |
| SMD2040 | Sn96.5/Ag3.0/Cu0.5 | 217-220°C (423-428°F) | 0.020" (0.5080mm) | 250,000 |
| SMD2040-25000 | Sn96.5/Ag3.0/Cu0.5 | 217-220°C (423-428°F) | 0.020" (0.5080mm) | 25,000 |
| SMD2050 | Sn96.5/Ag3.0/Cu0.5 | 217-220°C (423-428°F) | 0.024" (0.6096mm) | 250,000 |
| SMD2050-25000 | Sn96.5/Ag3.0/Cu0.5 | 217-220°C (423-428°F) | 0.024" (0.6096mm) | 25,000 |
| SMD2055 | Sn96.5/Ag3.0/Cu0.5 | 217-220°C (423-428°F) | 0.025" (0.6350mm) | 250,000 |
| SMD2055-25000 | Sn96.5/Ag3.0/Cu0.5 | 217-220°C (423-428°F) | 0.025" (0.6350mm) | 25,000 |
| SMD2060 | Sn96.5/Ag3.0/Cu0.5 | 217-220°C (423-428°F) | 0.030" (0.7620mm) | 250,000 |
| SMD2060-25000 | Sn96.5/Ag3.0/Cu0.5 | 217-220°C (423-428°F) | 0.030" (0.7620mm) | 25,000 |

Shelf Life: >24 months

Test Results

| Test J-STD-004 or other requirements as stated | Test Requirement | Result |
|--|--|--|
| Conflict Minerals Compliance | Electronic Industry Citizenship Coalition (EICC) | Compliant |
| REACH Compliance | Articles 33 and 67 of Regulation (EC) No 1907/2006 | Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials |

Conforms to the following Industry Standards:

J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):
RoHS 2 Directive 2011/65/EU:

Yes
Yes (Sn96.5/Ag3.0/Cu0.5) /
No (Sn63/Pb37)